© Copy	rial Composition yright 2005. IPC, B tional and Pan-Ame	annockbu	ırn, Illinois. A	ll rights reserved untions.	under both	This docum level parts,	ent is a decla	aration o on encor	of the substances mpasses all low	s within the manufact er level materials for	urer listed which the	item. Note: manufacture	if the item is an as r has engineering	ssembly with lower responsibility.	
					Form Type Distribute					rials and Mfg Information					
Supplier Information															
Company name*			Company unique ID			Unique ID Authority					Response Date*				
On Semiconductor											2021-0	2021-02-03			
Contact Name			Title - Contact			Phone - Contact*				Email	Email - Contact*				
Product-Env-Stewards			Product Enviro Compliance			NA				Produ	Product-Env-Stewards@onsemi.com				
Authorized Representative*			Title - Representative			Phone - Representative*			Email	Email - Representative*					
Product-Env-Stewards			Product Enviro Compliance			NA				Produ	Product-Env-Stewards@onsemi.com				
Requester Item Nu	mber N	r Mfr Item Numb		Jumber Mfr Item Name			Effective D	ate V	rsion	Manufacturing Site		Weight*	UOM	Unit Type	
	E	BC817-25LT1G		SS SOT23 GP XSTR NPN 45V			2021-02-03	3		CN1		8.02	mg	Each	
Manufacturing Procces	s Information							·							
Terminal Plating / C	Terminal Plating / Grid Array Material Terminal 1		erminal Base A	Alloy J-STD-020 MSL Rating		L Rating	Peak Process Body Temperature		are Max Time at Peak Tempera		mperature Number of Reflow Cycles		cles		
Matte Tin (Sn) - annealed CU Alle			U Alloy	1			260 C 30		30	seco	seconds 3				
Comments															
level 1 - maximum time at pea	ak temperature du	ring sold	lering is 10-3	0 seconds											
For more information regard	ing material comp	osition p	lease refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted						
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all						
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	stislav Drska	Le									

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.05	mg	Supplier	Silicon (Si)	7440-21-3		0.05	mg
Lead Frame	2.92	mg	В	Nickel (Ni)	7440-02-0		1.06	mg
			Supplier	Iron (Fe)	7439-89-6		1.4658	mg
			Supplier	Copper (Cu)	7440-50-8		0.3942	mg
Mold Compound-Black	4.9	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.49	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0245	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		0.7105	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		3.185	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.49	mg
Plating	0.14	mg	Supplier	Tin (Sn)	7440-31-5		0.14	mg
Wire Bond	0.01	mg	Supplier	Palladium (Pd)	7440-05-3		0.0001	mg
			Supplier	Copper (Cu)	7440-50-8		0.0099	mg